



SOT617-3

DFN5050-32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

8 June 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package type industry code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	-	-	0.85	-	mm
A ₂	package height	-	-	-	-	
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	32	-	

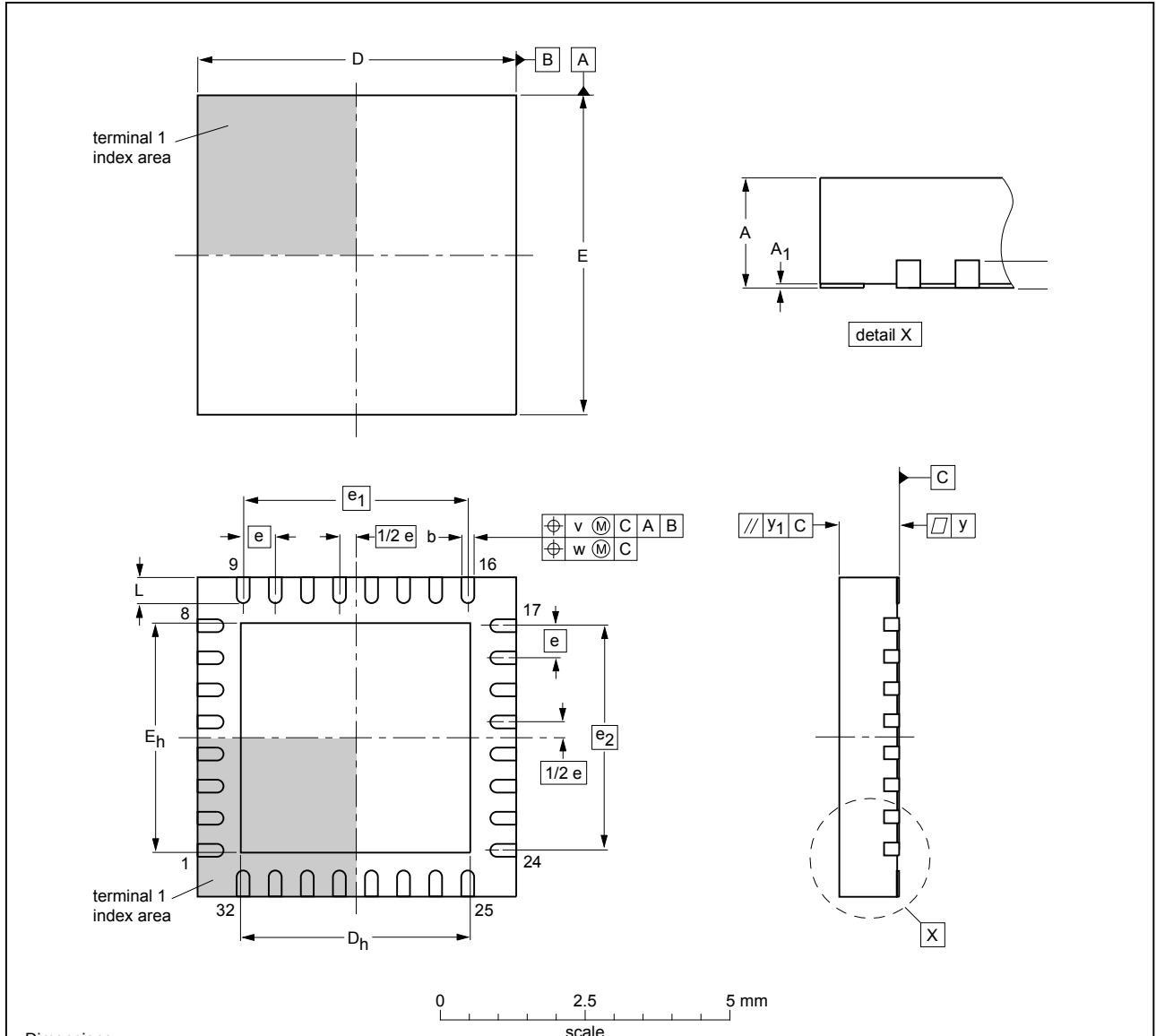


DFN5050-32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

2. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

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Dimensions

Unit ⁽¹⁾	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max		0.05	0.30		5.1	3.75	5.1	3.75				0.5				
nom	0.85			0.2					0.5	3.5	3.5		0.1	0.05	0.05	0.1
min		0.00	0.18		4.9	3.45	4.9	3.45				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT617-3		MO-220			-11-06-14- 11-06-21

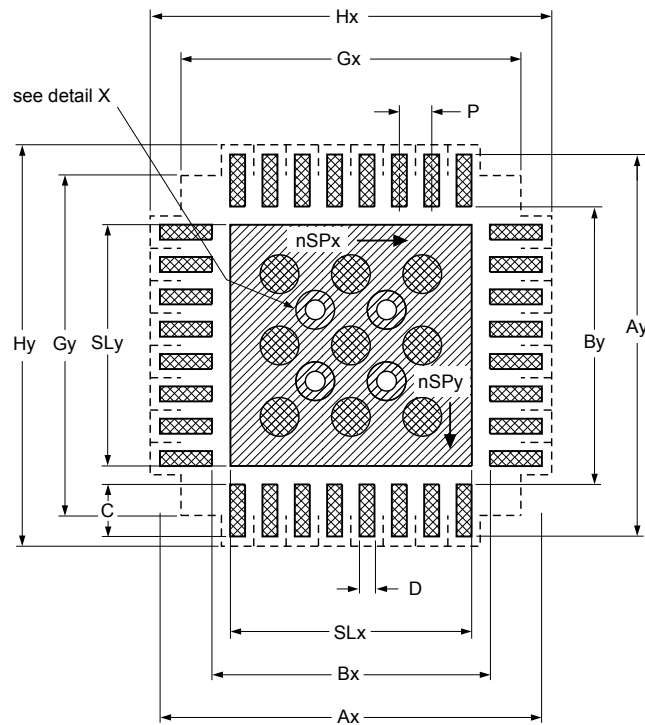
Fig. 1. Package outline HVQFN32 (SOT617-3)



DFN5050-32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

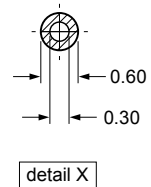
3. Soldering

Footprint information for reflow soldering of HVQFN32 package

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-  solder land
-  solder paste
- occupied area



Dimensions in mm

P	Ax	Ay	Bx	By	C	D	Gx	Gy	Hx	Hy	SLx	SLy	nSPx	nSPy
0.5	5.95	5.95	4.25	4.25	0.85	0.27	5.25	5.25	6.2	6.2	3.75	3.75	3	3

Issue date ~~11-11-15~~
11-11-20

sot617-3_fr

Fig. 2. Reflow soldering footprint for HVQFN32 (SOT617-3)

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4. Legal information

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